

**Assembly Relocation of Select LFCSP, Mini-LFCSP, LFCSP Side Solderable
Products to STATS ChipPAC China Jiangyin**

**Qualification Results Summary for
Mini-LFCSP at STATS ChipPAC China Jiangyin**

TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	PASS
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	PASS ±1250V

* Preconditioned per JEDEC/IPC J-STD0020.